

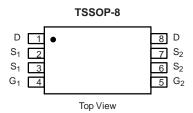
Dual N-Channel MOSFET

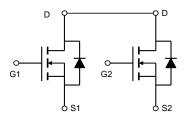
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
20	0.013 at V _{GS} = 4.5 V	7.6		
	0.020 at V _{GS} = 2.5 V	6.5		

FEATURES

- Halogen-free Option Available
- TrenchFET® Power MOSFETs







ABSOLUTE MAXIMUM RATINGS	TA = 20 0, arries			011-01-1-	1111
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	20		V
Gate-Source Voltage		V_{GS}	± 12		V
Continuous Danie Comment /T 450 90\8	T _A = 25 °C	- I _D	7.6	6.2	^
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		6.5	4.5	
Pulsed Drain Current		I _{DM}	30		Α
Continuous Source Current (Diode Conduction) ^a		I _S	1.5	1.0	
Maniana Bana Biasia dia d	T _A = 25 °C	- P _D	1.5	1.0	W
Maximum Power Dissipation ^a	T _A = 70 °C		0.96	0.64	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Тур.	Max.	Unit
Mariana da Arabianta	t ≤ 10 s	R _{thJA}	72	83	°C/W
Maximum Junction-to-Ambient ^a	Steady State		100	120	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	55	70	

Notes:

- a. Surface Mounted on FR4 board, $t \le 10$ s.
- * Pb containing terminations are not RoHS compliant, exemptions may apply.

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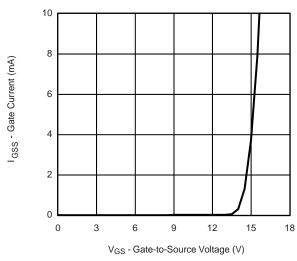


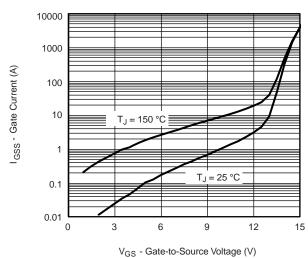
SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.6		1.6	V	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 200	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА	
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$			25		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	30			Α	
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 6.5 \text{ A}$		0.014	0.020	Ω	
		$V_{GS} = 2.5 \text{ V}, I_D = 5.5 \text{ A}$		0.018	0.030		
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 6.5 \text{ A}$		30		S	
Diode Forward Voltage ^b	V_{SD}	I _S = 1.5 A, V _{GS} = 0 V		0.71	1.2	V	
Dynamic ^a							
Total Gate Charge	Q_g			12	18		
Gate-Source Charge	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 6.5 \text{ A}$		2.2		nC	
Gate-Drain Charge	Q_{gd}			3.6			
Turn-On Delay Time	t _{d(on)}			245	365		
Rise Time	t _r	V_{DD} = 10 V, R_L = 10 Ω		330	495		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1 A, V_{GEN} = 4.5 V, R_G = 6 Ω		860	1300	ns	
Fall Time	t _f			510	765		

Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

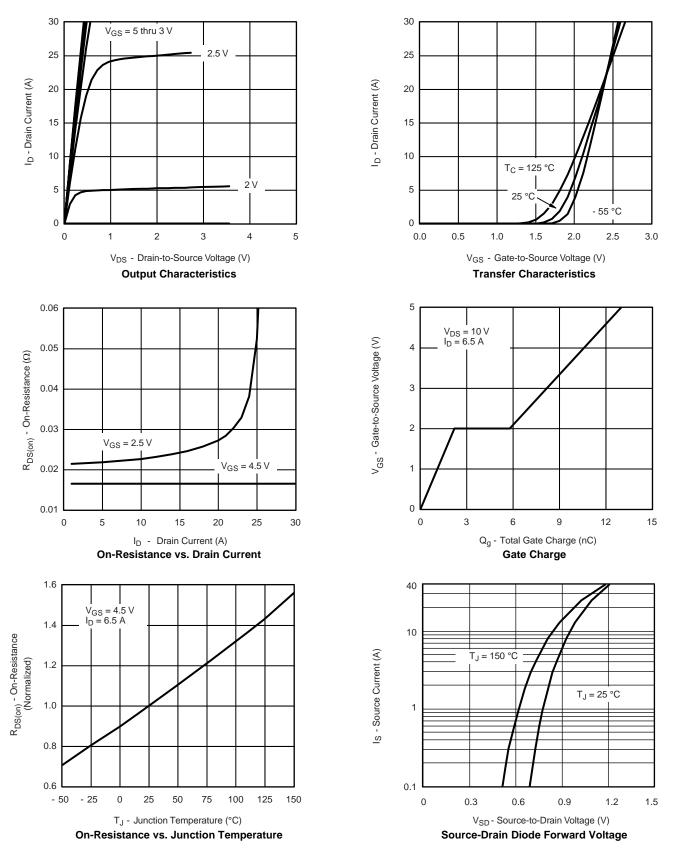
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



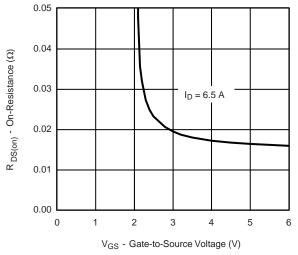


Gate Current vs. Gate-Source Voltage

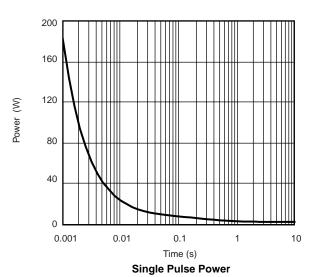






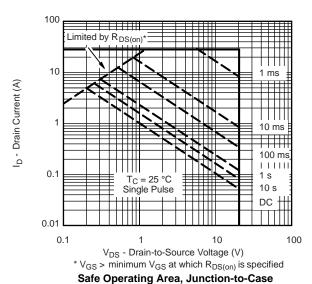


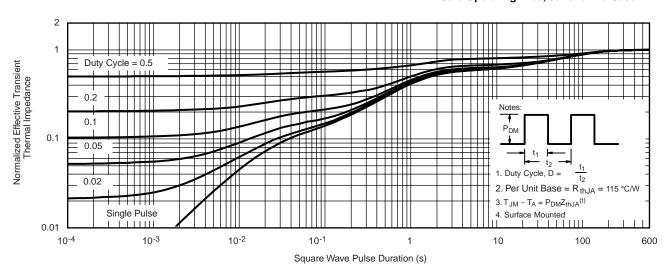
On-Resistance vs. Gate-to-Source Voltage



0.4 I_D = 250 μA 0.2 V_{GS(th)} Variance (V) 0.0 - 0.2 - 0.4 - 0.6 0 - 50 - 25 25 50 75 100 125 150 T_J - Temperature (°C)

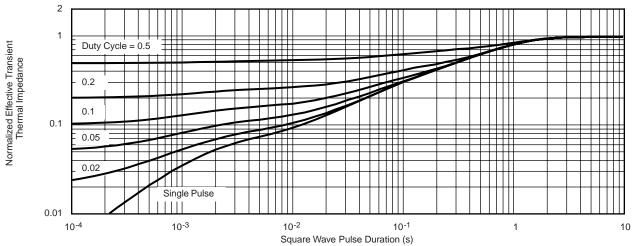
Threshold Voltage





Normalized Thermal Transient Impedance, Junction-to-Ambient

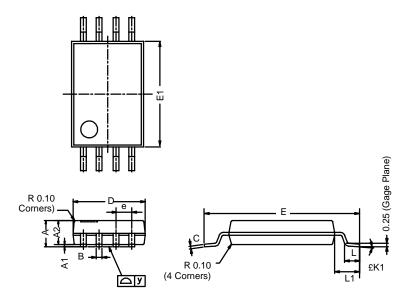






TSSOP: 8-LEAD

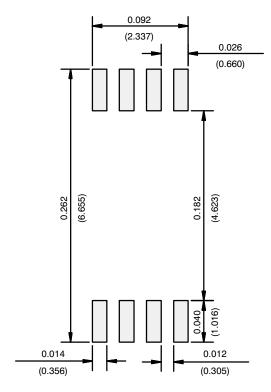
JEDEC Part Number: MO-153



	MILLIMETERS				
Dim	Min	Nom	Max		
Α	-	-	1.20		
A ₁	0.05	0.10	0.15		
A ₂	0.80	1.00	1.05		
В	0.19	0.28	0.30		
С	_	0.127	-		
D	2.90	3.00	3.10		
Е	6.20	6.40	6.60		
E ₁	4.30	4.40	4.50		
е	_	0.65	-		
L	0.45	0.60	0.75		
L ₁	0.90	1.00	1.10		
Y	_	-	0.10		
£K1	0°	3°	6°		
ECN: S-03946—Rev. G, 09-Jul-01 DWG: 5844					



RECOMMENDED MINIMUM PADS FOR TSSOP-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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